

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

# MOS FIELD EFFECT TRANSISTOR $\mu$ PA1793

# SWITCHING N- AND P-CHANNEL POWER MOS FET

### DESCRIPTION

The  $\mu$ PA1793 is N- and P-Channel MOS Field Effect Transistors designed for Motor Drive application.

### **FEATURES**

Low on-state resistance

N-Channel RDS(on)1 = 69 m $\Omega$  MAX. (Vgs = 4.5 V, ID = 1.5 A)

 $R_{DS(on)2} = 72 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 4.0 \text{ V, ID} = 1.5 \text{ A)}$ 

 $R_{DS(on)3} = 107 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 2.5 \text{ V, ID} = 1.0 \text{ A)}$ 

P-Channel RDS(on)1 = 115 m $\Omega$  MAX. (VGS = -4.5 V, ID = -1.5 A)

 $R_{DS(on)2} = 120 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = -4.0 \text{ V, ID} = -1.5 \text{ A)}$ 

RDS(on)3 = 190 m $\Omega$  MAX. (Vgs = -2.5 V, ID = -1.0 A)

Low input capacitance

N-Channel Ciss = 160 pF TYP.

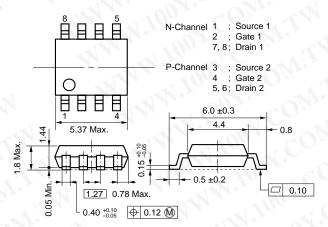
P-Channel Ciss = 370 pF TYP.

- Built-in G-S protection diode
- Small and surface mount package (Power SOP8)

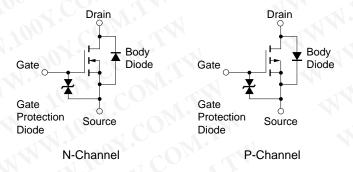
### ORDERING INFORMATION

PART NUMBER	PACKAGE
μPA1793G	Power SOP8

# PACKAGE DRAWING (Unit: mm)



### **EQUIVALENT CIRCUIT**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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# **ABSOLUTE MAXIMUM RATINGS (TA = 25°C, All terminals are connected.)**

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain to Source Voltage (Vgs = 0 V)	Voss	20	-20	٧
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	Vgss	± 12	∓ 12	V
Drain Current (DC)	I <sub>D(DC)</sub>	± 3	∓3	Α
Drain Current (pulse) Note1	D(pulse)	± 12	<b>∓</b> 12	A
Total Power Dissipation (1 unit) Note2	Рт	4	W	
Total Power Dissipation (2 units) Note2	Рт	2.0		W
Channel Temperature	Tch	1:	°C	
Storage Temperature	Tstg	–55 to	°C	

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

2. Mounted on ceramic substrate of 5500 mm<sup>2</sup>  $\times$  2.2 mm, T<sub>A</sub> = 25°C

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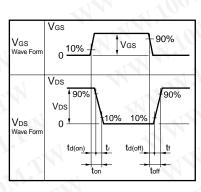
# **ELECTRICAL CHARACTERISTICS (TA = 25°C, All terminals are connected.)**

# A) N-Channel

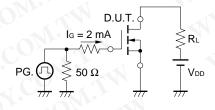
Characteristice	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V		M.	10	μΑ
Gate Leakage Current	lgss	V <sub>GS</sub> = ±12 V, V <sub>DS</sub> = 0 V			±10	μΑ
Gate Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.5	1.0	1.5	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> = 10 V, I <sub>D</sub> =1.5 A	1.0		7.	S
Drain to Source On-state Resistance	R <sub>DS(on)1</sub>	Vgs = 4.5 V, ID = 1.5 A		55	69	mΩ
	RDS(on)2	Vgs = 4.0 V, ID = 1.5 A		57	72	mΩ
	R <sub>DS(on)3</sub>	V <sub>G</sub> S = 2.5 V, I <sub>D</sub> = 1.0 A	100	78	107	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V	N	160		pF
Output Capacitance	Coss	V <sub>G</sub> S = 0 V		60	1	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		40	<b>0</b> ^ 1	pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 10 V, I <sub>D</sub> = 1.5 A		17	007	ns
Rise Time	tr	V <sub>G</sub> S = 4.0 V		50		ns
Turn-off Delay Time	td(off)	R <sub>G</sub> = 10 Ω		86	170	ns
Fall Time	tf	COM		80	11	ns
Total Gate Charge	QG	V <sub>DD</sub> = 16 V		3.1		nC
Gate to Source Charge	Qgs	V <sub>G</sub> S = 4.0 V	-	0.7		nC
Gate to Drain Charge	Q <sub>GD</sub>	ID = 3.0 A		1.4		nC
Body Diode Forward Voltage	V <sub>F</sub> (S-D)	IF = 3.0 A, VGS = 0 V		0.86		٧
Reverse Recovery Time	trr	IF = 3 A, VGS = 0 V		70		ns
Reverse Recovery Charge	Qrr	di/dt = 50 A/μs	1	12		nC

# **TEST CIRCUIT 1 SWITCHING TIME**

# D.U.T. PG. RG RG VDD $\tau = 1 \mu s$ Duty Cycle $\leq 1\%$



# **TEST CIRCUIT 2 GATE CHARGE**



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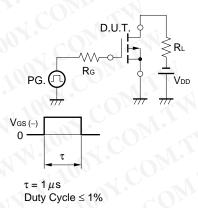
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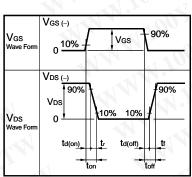


B) P-Channel

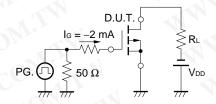
Characteristics	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Zero Gate Voltage Drain Current	loss	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V			-10	μΑ
Gate Leakage Current	lgss	V <sub>G</sub> S = ∓ 12 V, V <sub>D</sub> S = 0 V			∓10	μΑ
Gate Cut-off Voltage	V <sub>GS(off)</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.5	-1.0	-1.5	V
Forward Transfer Admittance	yfs	$V_{DS} = -10 \text{ V}, I_{D} = -1.5 \text{ A}$	1.0	Oz		S
Drain to Source On-state Resistance	RDS(on)1	$V_{GS} = -4.5 \text{ V}, I_{D} = -1.5 \text{ A}$	007	75	115	mΩ
	RDS(on)2	Vgs = -4.0 V, ID = -1.5 A		80	120	mΩ
	RDS(on)3	Vgs = −2.5 V, ID = −1.0 A	u 1	116	190	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = -10 V	10	370	0	pF
Output Capacitance	Coss	Vgs = 0 V		110		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		40		pF
Turn-on Delay Time	td(on)	$V_{DD} = -10 \text{ V}, \text{ ID} = -1.5 \text{ A}$		120	0 - 1	ns
Rise Time	tr	Vgs = -4.0 V		260	003	ns
Turn-off Delay Time	td(off)	$R_G = 10 \Omega$		410	-	ns
Fall Time	tr			360		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = -10 V		3.4	1	nC
Gate to Source Charge	QGS	Vgs = -4.0 V		1.3		nC
Gate to Drain Charge	Q <sub>GD</sub>	$I_D = -3.0 \text{ A}$		1.6		nC
Body Diode Forward Voltage	VF(S-D)	IF = 3.0 A, VGS = 0 V		0.86		V
Reverse Recovery Time	trr	IF = 3 A, VGS = 0 V		24		ns
Reverse Recovery Charge	Qrr	$di/dt = 10 A/\mu s$	N	1.5		nC

# TEST CIRCUIT 1 SWITCHING TIME





# **TEST CIRCUIT 2 GATE CHARGE**

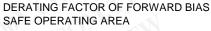


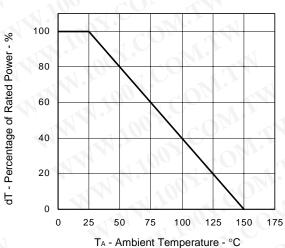
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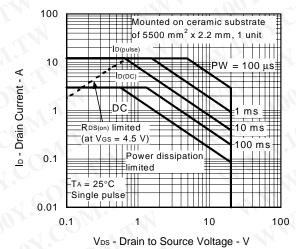
# TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

### A) N-Channel

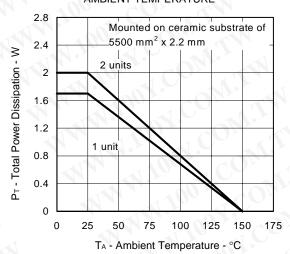




### FORWARD BIAS SAFE OPERATING AREA

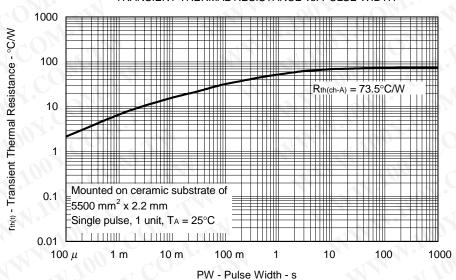


# TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



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### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



5

# NEC

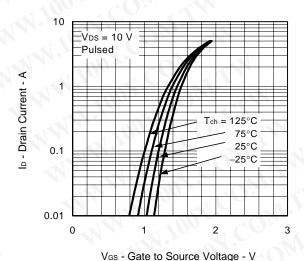
A) N-Channel

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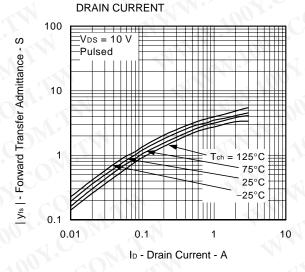
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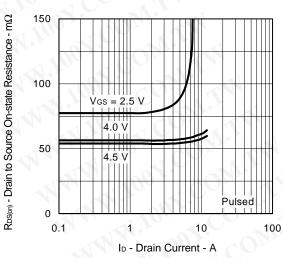
### FORWARD TRANSFER CHARACTERISTICS



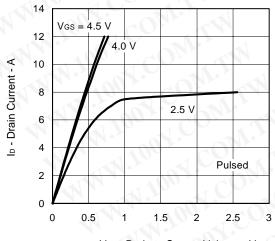
FORWARD TRANSFER ADMITTANCE vs.



DRAIN TO SOURCE ON-STATE RESISTANCE vs DRAIN CURRENT

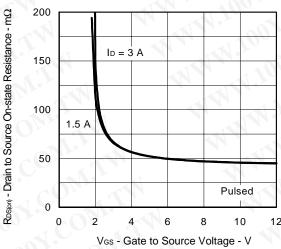


# DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

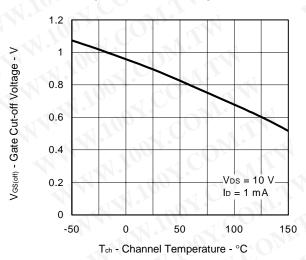


V<sub>DS</sub> - Drain to Source Voltage - V

# DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE

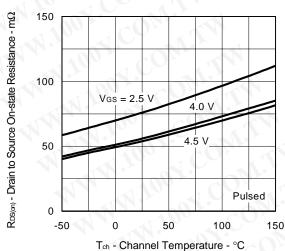


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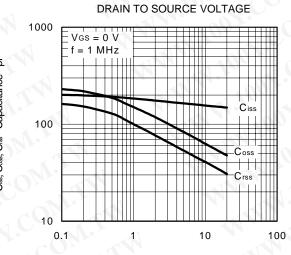
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# A) N-Channel

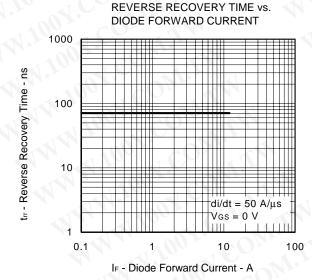
# DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



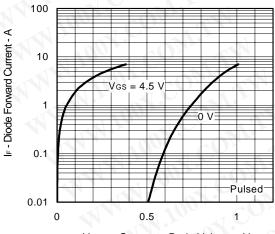
# CAPACITANCE vs.



V<sub>DS</sub> - Drain to Source Voltage - V

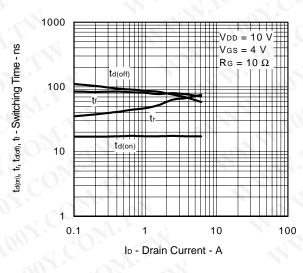


# SOURCE TO DRAIN DIODE FORWARD VOLTAGE

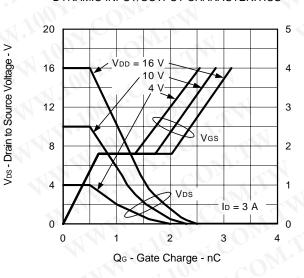


V<sub>F(S-D)</sub> - Source to Drain Voltage - V

# SWITCHING CHARACTERISTICS

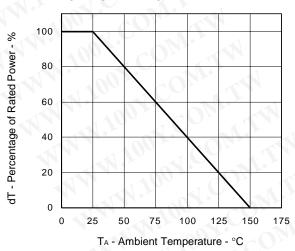


### DYNAMIC INPUT/OUTPUT CHARACTERITICS

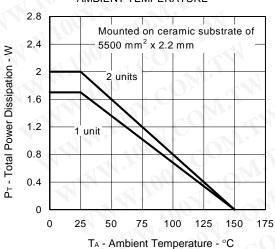


### B) P-Channel

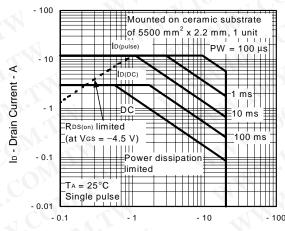
# DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



# TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



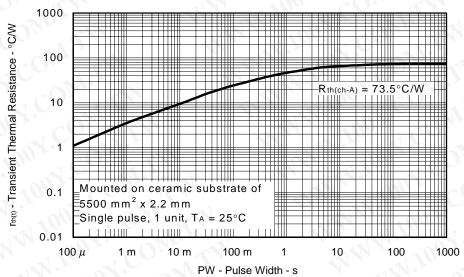
### FORWARD BIAS SAFE OPERATING AREA



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V<sub>DS</sub> - Drain to Source Voltage - V

# TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

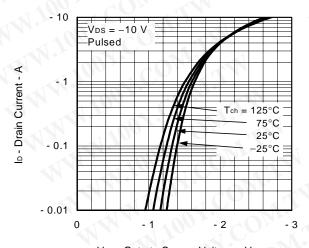


B) P-Channel

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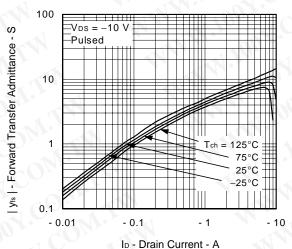
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### FORWARD TRANSFER CHARACTERISTICS

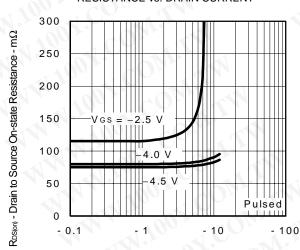


V<sub>GS</sub> - Gate to Source Voltage - V

# FORWARD TRANSFER ADMITTANCE vs DRAIN CURRENT

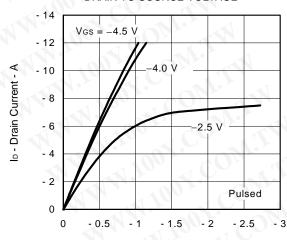


DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



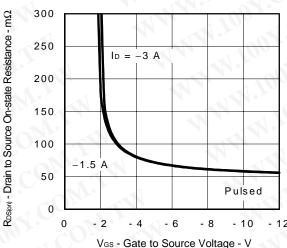
ID - Drain Current - A

# DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

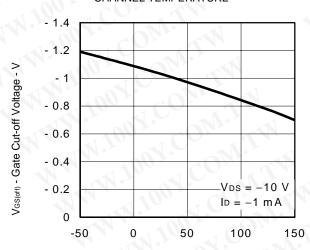


V<sub>DS</sub> - Drain to Source Voltage - V

### DRAIN TO SOURCE ON-STATE RESISTANCE vs GATE TO SOURCE VOLTAGE



GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE

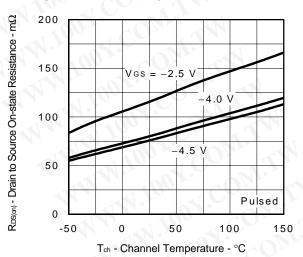


Tch - Channel Temperature - °C

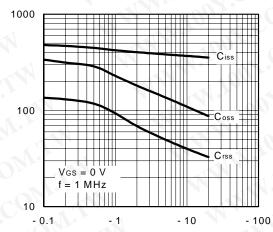
# NEC

# ) P-Channel

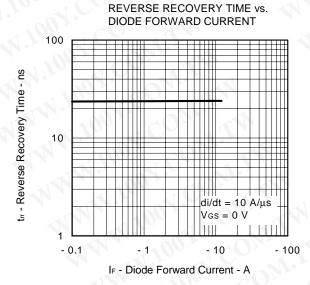
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



CAPACITANCE vs.
DRAIN TO SOURCE VOLTAGE

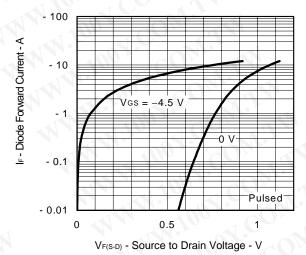


V<sub>DS</sub> - Drain to Source Voltage - V

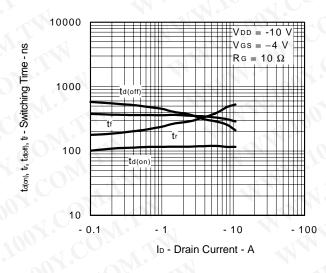


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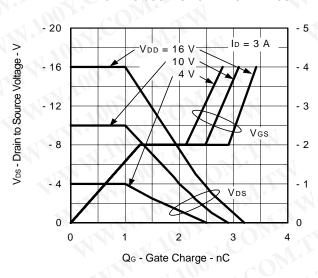
# SOURCE TO DRAIN DIODE FORWARD VOLTAGE



SWITCHING CHARACTERISTICS



## DYNAMIC INPUT/OUTPUT CHARACTERITICS



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